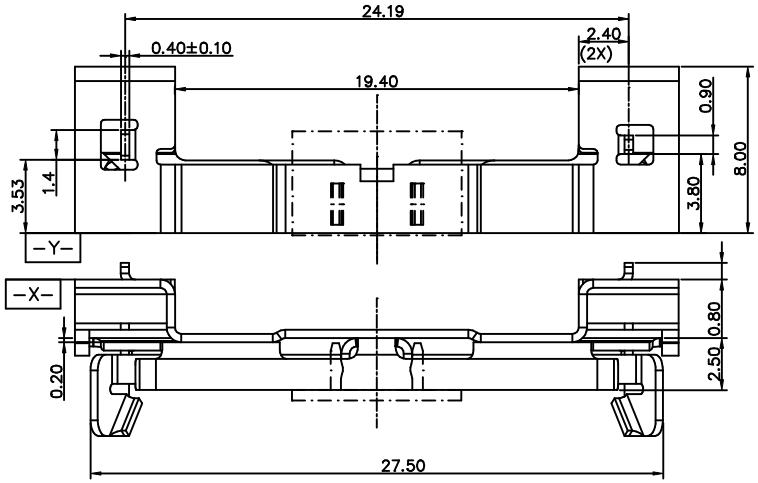
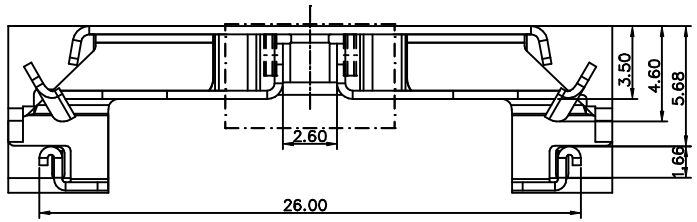
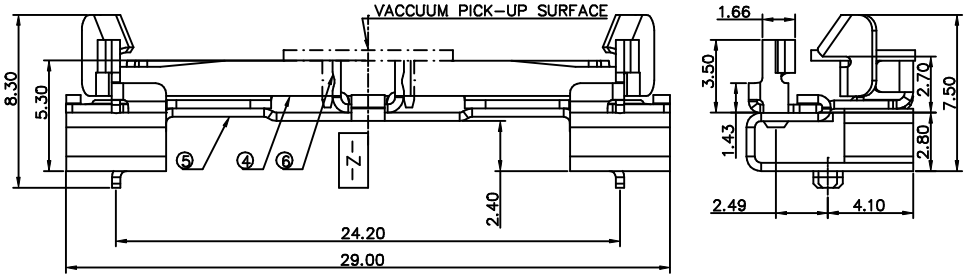
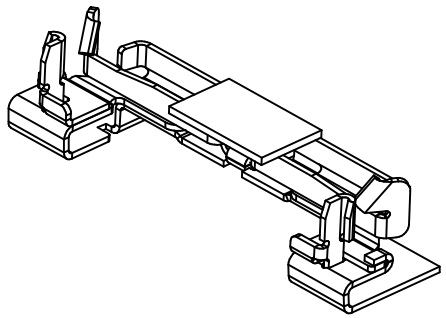
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND

REV.	ECN. NO.	APPD.









SPECIFICATIONS:

1. ELECTRICAL CHARACTERISTICS:
1-1 CURRENT RATING: 0.75 A MAX per power contact.
1-2 VOLTAGE RATING: 50 VAC per contact.
1-3 LOW LEVEL CONTACT RESISTANCE: 55mΩ max. initial, ΔR =20mΩmax.
1-4 INSULATION RESISTANCE: 500MΩ min. at 500 V DC.
1-5 DIELECTRIC WITHSTANDING VOLTAGE: 300 V AC (RMS).
1-6 INSERTION LOSS: f ≤1.25 GHz: ≤1dB; 1.25 <f≤3.75 GHz: ≤1.6x(f-1.25)+1dB
1-7 RETURN LOSS: f ≤1.3GHz: ≤-12dB; 1.3<f≤2GHz: ≤-7dB; 2<f≤3.75GHz: ≤-4dB
1-8 CROSSTALK NEXT: f≤1.25GHz: ≤-32dB; 1.25<f≤3.75GHz: ≤-(32-2.4x(f-1.25)) dB
1-9 TEMPERATURE RISE VERSUS CURRENT: <30°C at rated current per EIA-364-70A, method 2.
2. MECHANICAL CHARACTERISTICS:
2-1 DURABILITY: 50 mating/unmating cycles.
2-2 MATING/UNMATING FORCE: 2.3 kgf max. per connector.
3. ENVIRONMENTAL CHARACTERISTICS:
3-1 USEFUL FIELD LIFE: 5 years.
3-2 OPERATING TEMPERATURE: -40°C TO +80°C.
3-3 TEMPERATURE LIFE: Subject mated samples at 105±2°C for 120 hours per EIA-364-17, method A.
3-4 THERMAL SHOCK: Subject mated samples to 10 cycles between -55 to 85°C per EIA-364-32C, condition I.
3-5 CYCLIC TEMPERATURE & HUMIDITY: Subject mated samples to 24 cycles between 25°C at 80% RH to 65°C at 50% RH per EIA-364-31B.
3-6 VIBRATION: Subject mated samples to 20 to 500 Hz, 3.1 g RMS random excitation of 15 min. in each of the 3 axes and no discontinuity >1μs is found per EIA-364-28D, test condition VII, test condition letter D.
3-7 MECHANICAL SHOCK: Subject mated samples to 50% half-sine excitation of 11 ms duration and no discontinuity >1μs is found per per EIA-364-27B, condition A.
3-8 MIXED FLOWING GAS: Subject mated samples for 7 days per EIA-364-65, class IIA.
3-9 THERMAL DISTURBANCE: Subject mated samples to 10 cycles between 15 to 85°C.
4. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS & AVAILABILITY.

ITEM	DESCRIPTION	Q'TY	METERIAL	TREATMENT
⑥	CAP	1	THERMOPLASTIC	UL94V-0, IVORY COLOR(IN ORDER TO PICK-UP,TAKE AWAY AFTER ASSEMBLY)
⑤	CLIP(2)	1	STANLESS STEEI	Pd PLATING OVER SOLDER PAD AREA
④	CLIP(1)	1	STANLESS STEEI	NO PLATING
③	BOARD LOCK	2	COPPER ALLOY	PURE TIN OVER ALL
②	CONTACT	52	PHOSPHOR BRONZE	NICKEL UNDER PLATING GOLD PLATING AT CONTACT AREA
①	HOUSING	1	THERMOPLASTIC	UL94V-0, IVORY COLOR

X.± 0.30	X.°±	UNITS mm	NAME(INTENDED USE): MINI PCI EXPRESS Connector
.X± 0.25	.X°±	MAT'L	
.XX± 0.15	.XX°±	FINISH	PART NO.(INTENDED USE): AS0B22*-S68*-**
.XXX±	.XXX°±	Q'TY	APPD: Bruce Wu 4/23'06
			CHKD: Herry Yang 4/23'06
			DR: Rechard.XIAO 4/21'06

FOXCONN
HON HAI PRECISION IND. CO.,LTD.
TAIPEI, TAIWAN, R.O.C.

TITLE: CUSTOMER DRAWING

DWG NO.: 317-0000-1228

SCALE	SHEET	REV.
N/A	2/6	A

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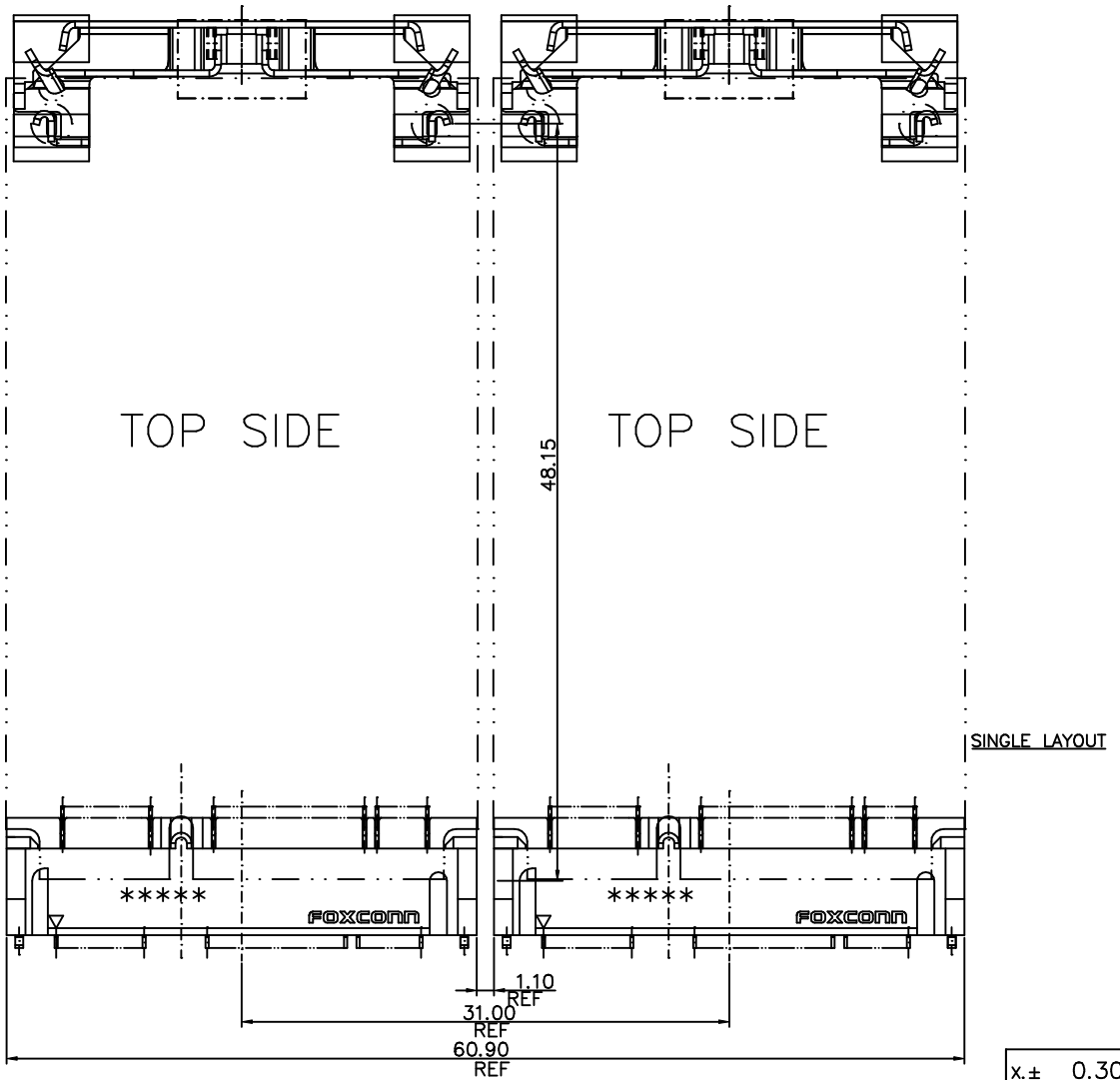
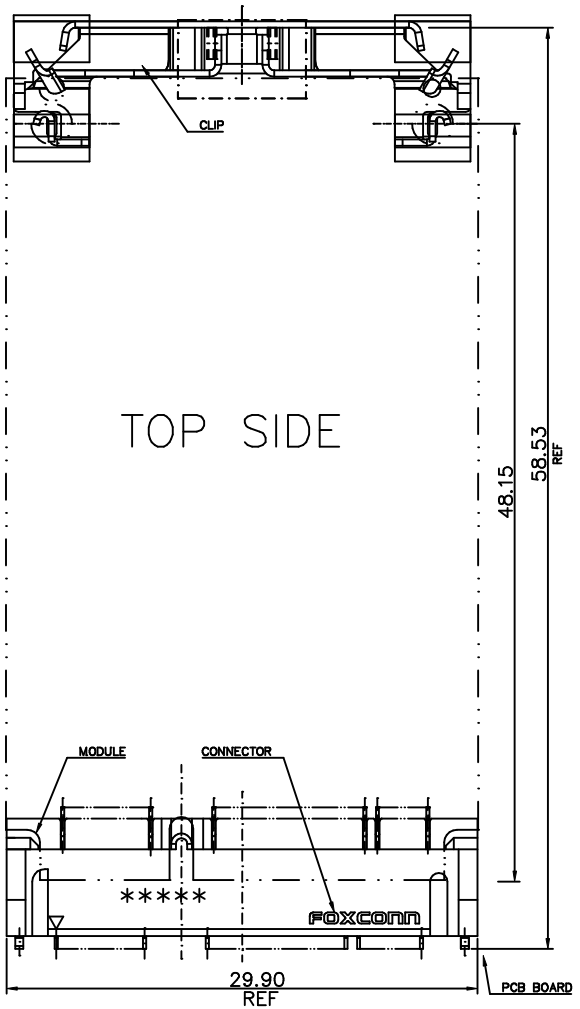
REV.	ECN. NO.	APPD.



SIDE BY SIDE LAYOUT FOR ASSEMBLLY(CONNECTOR+CLIP+MODULE CARD+P.C.B)

SINGLE LAYOUT



SINGLE LAYOUT FOR ASSEMBLLY(CONNECTOR+CLIP+MODULE CARD+P.C.B)

x.± 0.30	x°±	UNITS mm	NAME(INTENDED USE) MINI PCI EXPRESS Connector
.x± 0.25	.x°±	MAT'L	
.xx± 0.15	.xx°±		PART NO.(INTENDED USE) AS0B22*-S68*-**
.XXX±	.XXX°±	FINISH	APPD: Bruce Wu 4/23'06
		Q'TY	CHKD: Herry Yang 4/23'06
			DR: Rechard.XIAO 4/21'06

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HON HAI PRECISION IND. CO.,LTD.
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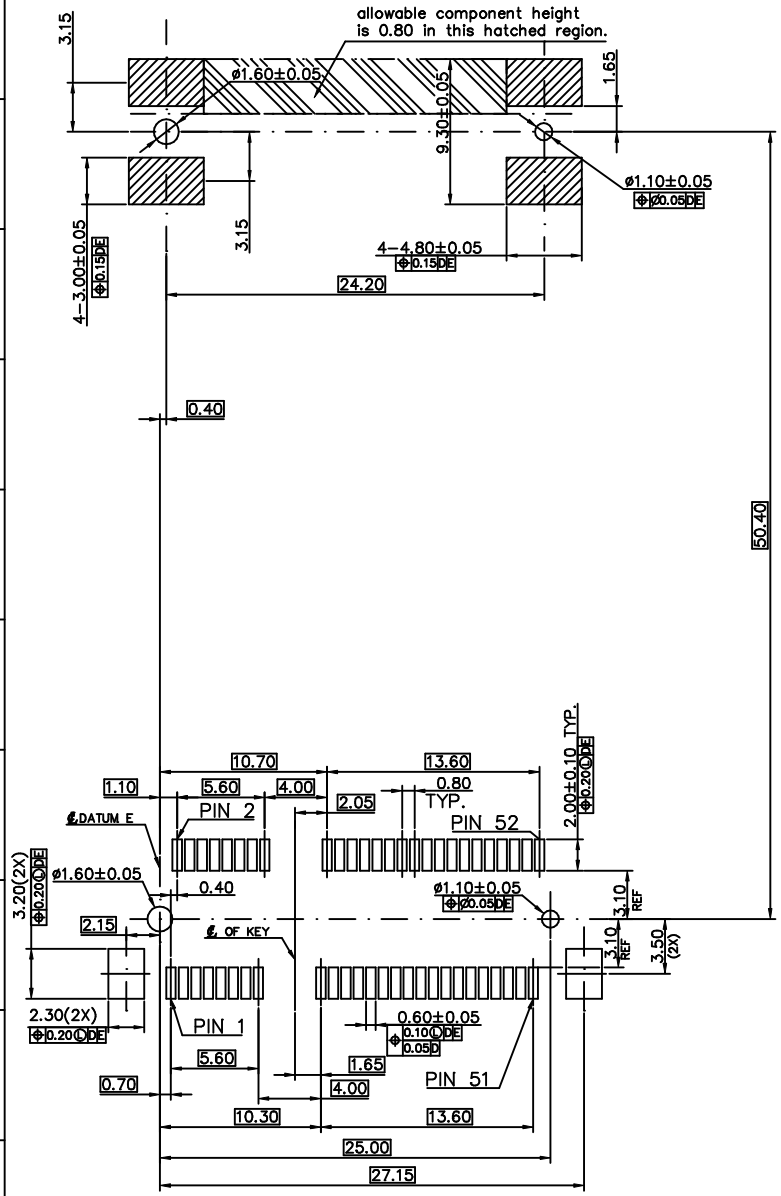
TITLE: CUSTOMER DRAWING

DWG NO.: 317-0000-1228

SCALE	SHEET	REV.
N/A	3/6	A

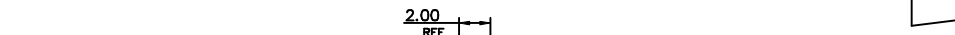
IDEAS GENERATED DRAWING, DO NOT CHANGE BY HAND

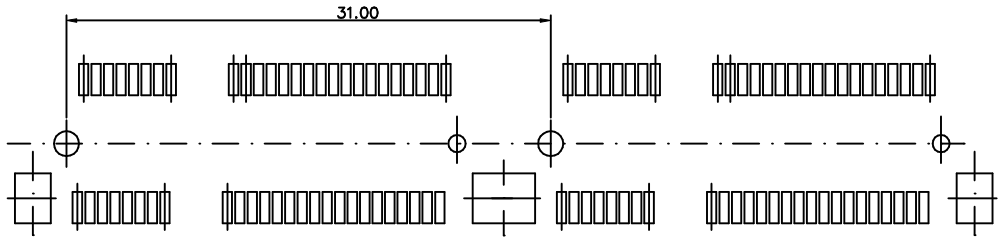
REV.	ECN. NO.	APPD.



*Datum is the top surface of PCB

RECOMMENFED P.C.B. BOARD LAYOUT





RECOMMENFED P.C.B. BOARD LAYOUT
(SIDE BY SIDE)

x.± 0.30	x°±	UNITS	mm
.x± 0.25	.x°±	MAT'L	
.xx± 0.15	.xx°±	FINISH	
.xxx±	.xxx°±	Q'TY	

NAME(INTENDED USE)	MINI PCI EXPRESS Connector
PART NO.(INTENDED USE)	AS0B22*-S68*-**
APPD:	Bruce Wu 4/23'06
CHKD:	Herry Yang 4/23'06
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TITLE: CUSTOMER DRAWING

DWG NO.: 317-0000-1228

SCALE	SHEET	REV.
N/A	5/6	A